IFETC was first held in Ottawa, Canada in 2018, and then Vancouver, Canada in 2019. IFETC2020 in Shanghai, China will follow the previous ones, and provide attendees with a unique opportunity to share, discuss and witness new concepts, new ideas and know-hows in flexible electronics technologies and their applications. We cordially invite submissions in following areas (but not limited to), addressing the technical challenges for flexible/foldable/stretchable devices, circuits and systems:

- Materials and Processes (MAP)
- Energy Harvesting and Storage (EHS)
- Sensors, Actuators and Bioelectronics (SAB)
- Hybrid Integration and Applications (HIA)
- Transistors and Electronic Devices (TED)
- Emissive and Reflective Displays (ERD)
- Circuits and Systems (CAS)

Prospective authors should recommend a technical category based on the detailed descriptions in the flyer when submitting their papers. The papers should be prepared using the given IEEE abstract template in two-page, and submitted as PDF files using the online submission system. Preference for oral or poster presentation format needs to be indicated.

The IFETC2020 papers will be subjected to IEEE-EDS standard review processes and IEEE conference publishing guidelines. Papers must clearly state the purpose of the work, the manner and degree to which it advances the art accompanied by proper references, and specific new results that have been obtained with clear experimental conditions and their significance.
The accepted papers presented at the conference will be published in the IFETC2020 proceedings and may be available on IEEE Xplore. Besides, the authors of a selected number of high quality presented papers will be invited to submit an extended version of the same for the consideration of publication in the IEEE Journal of Electron Devices Society (J-EDS). All such submissions must comply with J-EDS author-guidelines and be subjected to the standard IEEE and J-EDS publication policy.

**Highlights**

- Plenary presentations by prominent experts in interdisciplinary areas
- Focus sessions covering topics in:
  - Brain-computer interface
  - Interfacing electronics with biology
  - Device-circuit interaction
  - Scalable manufacturing
  - Heterogeneous and hybrid integration
- Panel discussion: “What is the next big thing of flexible electronics?”
- Tutorials on RFID, 3D printing, flexible displays, wearable sensor systems, …
- Three days of technical presentations organized into several parallel sessions. The conference will also include poster presentations.

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